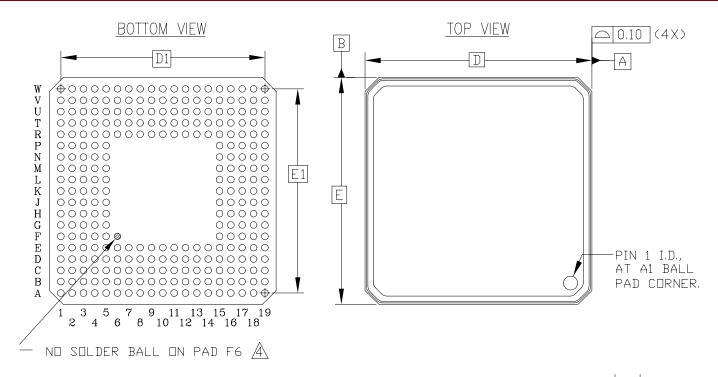
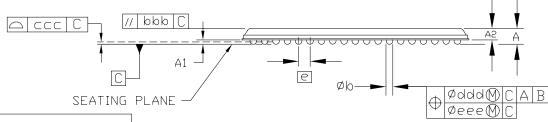
Chip Scale BGA (CS280) Package





S Y M B	MILLIMETERS		
	MIN.	N□M.	MAX.
А	*	*	1.20
Α1	0.20	*	*
Αz	0.65	**	*
D/E	16.00 BSC		
D ₁ /E ₁	14.40 BSC		
e	0.80 BSC		
Øb	0.40	0.45	0,50
bbb	*	*	0.10
CCC	4	14	0.12
ddd	*	14	0.15
666	4	14	0.08
М	19		
	A A1 A2 D/E D1/E1 e Øb bbb ccc ddd eeee	MIN. A	MIN. NOM. A

NOTES:

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
- 2. SYMBOL "M" IS THE PIN MATRIX SIZE.
- 3. CONFORMS TO JEDEC MO-216-BAL-1 (DEPOPULATED).
- A. PAD 'F6' IS FOR PAD 'A1' CORNER INDICATION.

280-BALL CHIP SCALE BGA (CS280)

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